

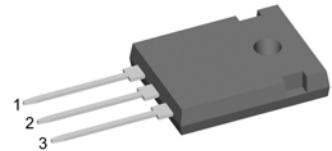
Thyristor

V_{RRM} = 1600V
 I_{TAV} = 50A
 V_T = 1.31V

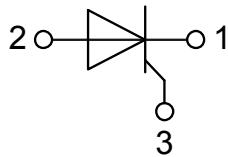
Single Thyristor

Part number

CMA50E1600HB



Backside: anode



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

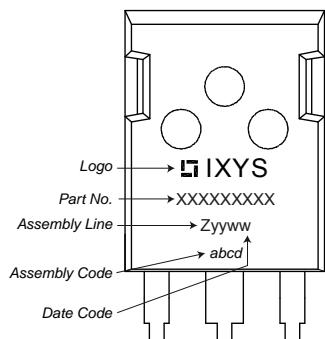
Package: TO-247

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- High creepage distance between terminals

Thyristor			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1700	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1600	V
I_{RD}	reverse current, drain current	$V_{RD} = 1600 V$ $V_{RD} = 1600 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		50 5	μA mA
V_T	forward voltage drop	$I_T = 50 A$ $I_T = 100 A$ $I_T = 50 A$ $I_T = 100 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		1.30 1.66 1.31 1.77	V V
I_{TAV}	average forward current	$T_C = 110^\circ C$	$T_{VJ} = 150^\circ C$		50	A
$I_{T(RMS)}$	RMS forward current	180° sine			79	A
V_{TO} r_T	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 150^\circ C$		0.83 9.6	V $m\Omega$
R_{thJC}	thermal resistance junction to case				0.4	K/W
R_{thCH}	thermal resistance case to heatsink			0.25		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		310	W
I_{TSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 150^\circ C$ $V_R = 0 V$		550 595 470 505	A
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$ $t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $T_{VJ} = 150^\circ C$ $V_R = 0 V$		1.52 1.48 1.11 1.06	kA²s
C_J	junction capacitance	$V_R = 400 V$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	26		pF
P_{GM}	max. gate power dissipation	$t_p = 30 \mu s$ $t_p = 300 \mu s$	$T_C = 150^\circ C$		10 5 0.5	W W W
P_{GAV}	average gate power dissipation					
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 150^\circ C; f = 50 \text{ Hz}$ repetitive, $I_T = 150 A$ $t_p = 200 \mu s; di_G/dt = 0.3 A/\mu s;$ $I_G = 0.3 A; V_D = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 50 A$			150	A/ μs
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$; method 1 (linear voltage rise)	$T_{VJ} = 150^\circ C$		1000	V/ μs
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$		1.5 1.6	V
I_{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$		50 80	mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 140^\circ C$		0.2	V
I_{GD}	gate non-trigger current				5	mA
I_L	latching current	$t_p = 10 \mu s$ $I_G = 0.3 A; di_G/dt = 0.3 A/\mu s$	$T_{VJ} = 25^\circ C$		125	mA
I_H	holding current	$V_D = 6 V$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ C$		100	mA
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$ $I_G = 0.3 A; di_G/dt = 0.3 A/\mu s$	$T_{VJ} = 25^\circ C$		2	μs
t_q	turn-off time	$V_R = 100 V; I_T = 50 A; V_D = \frac{2}{3} V_{DRM}$ $T_{VJ} = 150^\circ C$ $di/dt = 10 A/\mu s; dv/dt = 20 V/\mu s; t_p = 200 \mu s$		150		μs

Package TO-247			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			70	A
T_{stg}	storage temperature		-55		150	°C
T_{VJ}	virtual junction temperature		-40		150	°C
Weight				6		g
M_D	mounting torque		0.8		1.2	Nm
F_c	mounting force with clip		20		120	N

Product Marking



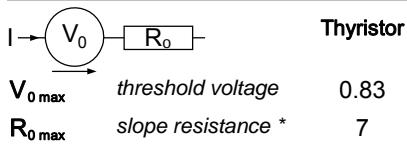
Part number

C = Thyristor (SCR)
M = Thyristor
A = (up to 1800V)
50 = Current Rating [A]
E = Single Thyristor
1600 = Reverse Voltage [V]
HB = TO-247AD (3)

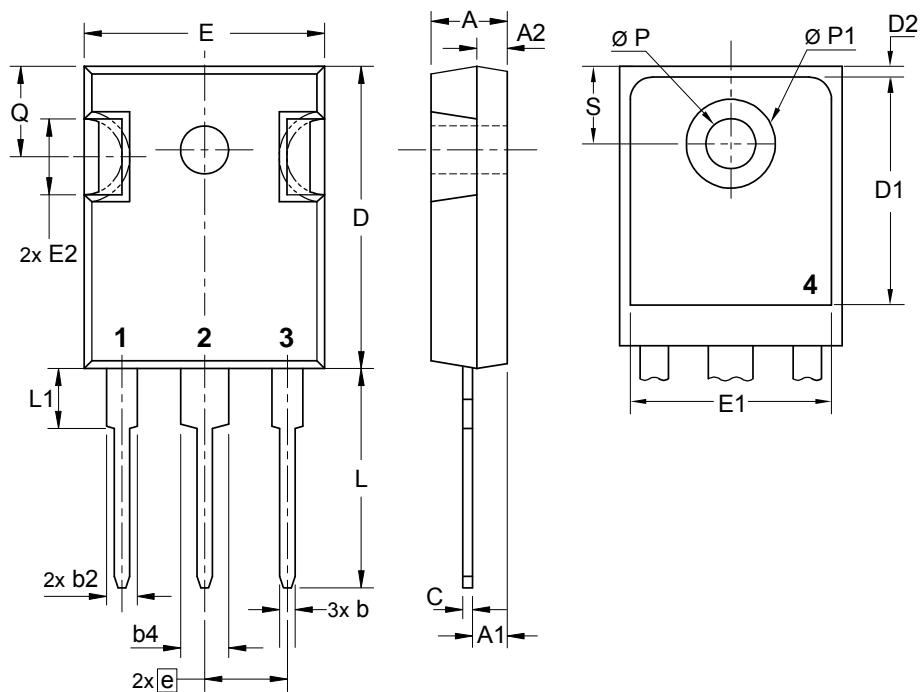
Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CMA50E1600HB	CMA50E1600HB	Tube	30	513974

Equivalent Circuits for Simulation

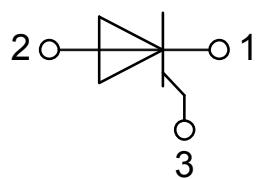
* on die level

 $T_{VJ} = 150 \text{ }^{\circ}\text{C}$ 

Outlines TO-247



Sym.	Inches min. max.	Millimeter min. max.
A	0.185 0.209	4.70 5.30
A1	0.087 0.102	2.21 2.59
A2	0.059 0.098	1.50 2.49
D	0.819 0.845	20.79 21.45
E	0.610 0.640	15.48 16.24
E2	0.170 0.216	4.31 5.48
e	0.215 BSC	5.46 BSC
L	0.780 0.800	19.80 20.30
L1	- 0.177	- 4.49
Ø P	0.140 0.144	3.55 3.65
Q	0.212 0.244	5.38 6.19
S	0.242 BSC	6.14 BSC
b	0.039 0.055	0.99 1.40
b2	0.065 0.094	1.65 2.39
b4	0.102 0.135	2.59 3.43
c	0.015 0.035	0.38 0.89
D1	0.515 -	13.07 -
D2	0.020 0.053	0.51 1.35
E1	0.530 -	13.45 -
Ø P1	- 0.29	- 7.39



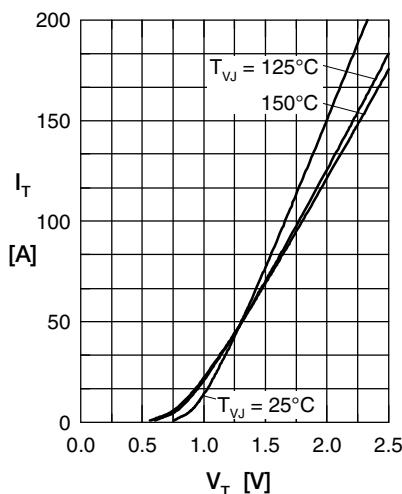
Thyristor

Fig. 1 Forward characteristics

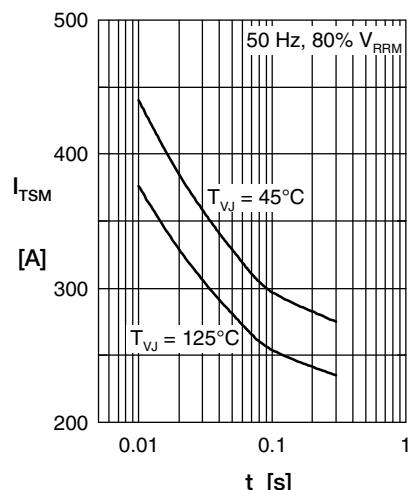
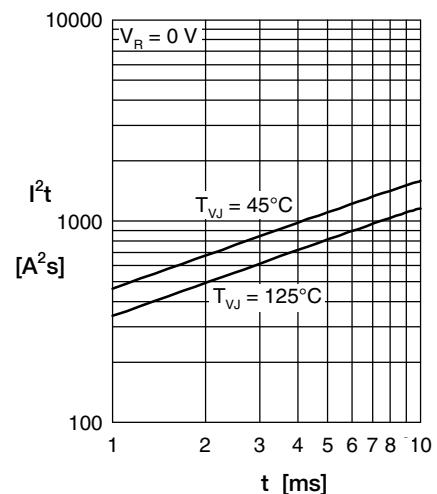
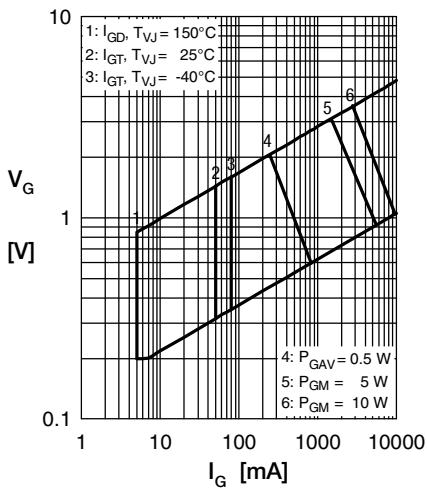
Fig. 2 Surge overload current
 I_{TSM} : crest value, t : durationFig. 3 I^2t versus time (1-10 s)

Fig. 4 Gate voltage & gate current

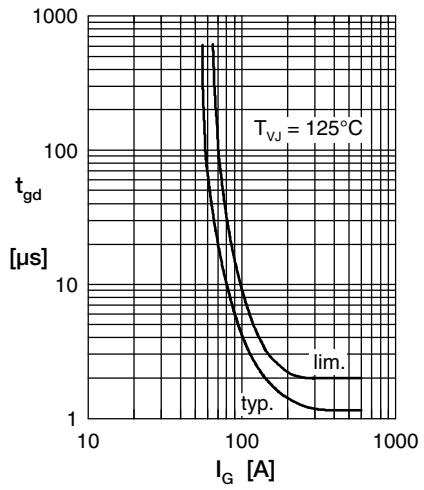
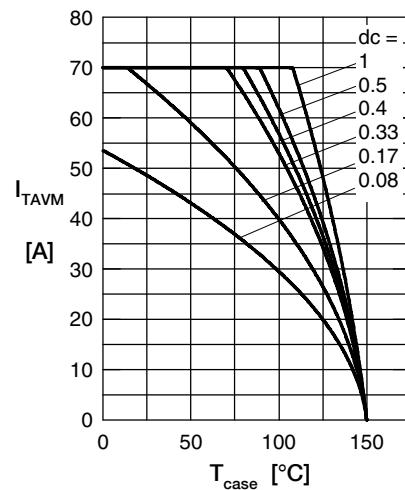
Fig. 5 Gate controlled delay time t_{gd} 

Fig. 6 Max. forward current at case temperature

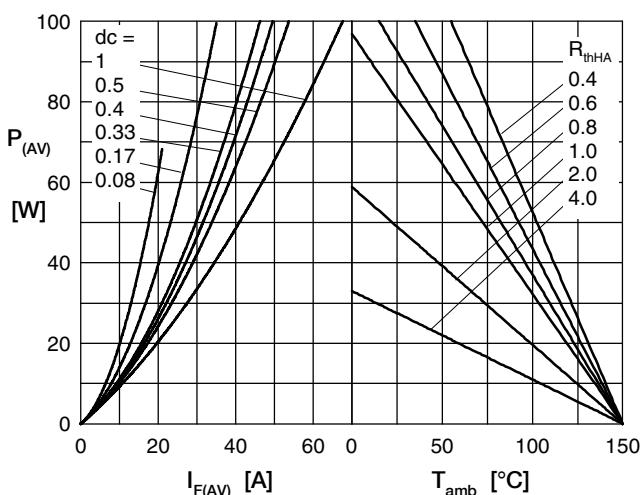
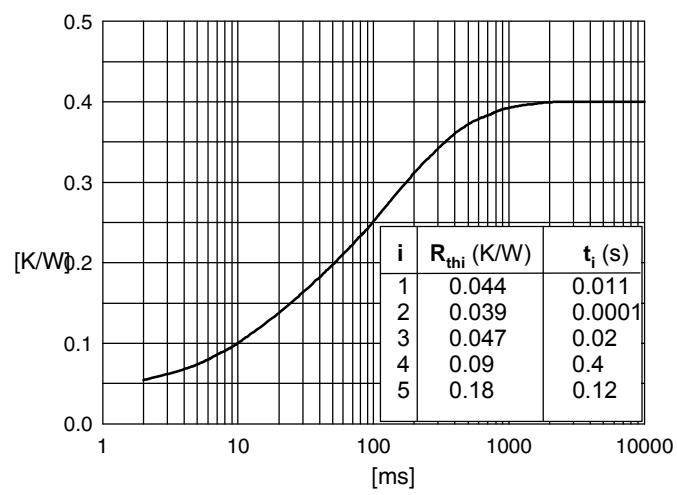
Fig. 7a Power dissipation versus direct output current
Fig. 7b and ambient temperature

Fig. 7 Transient thermal impedance junction to case